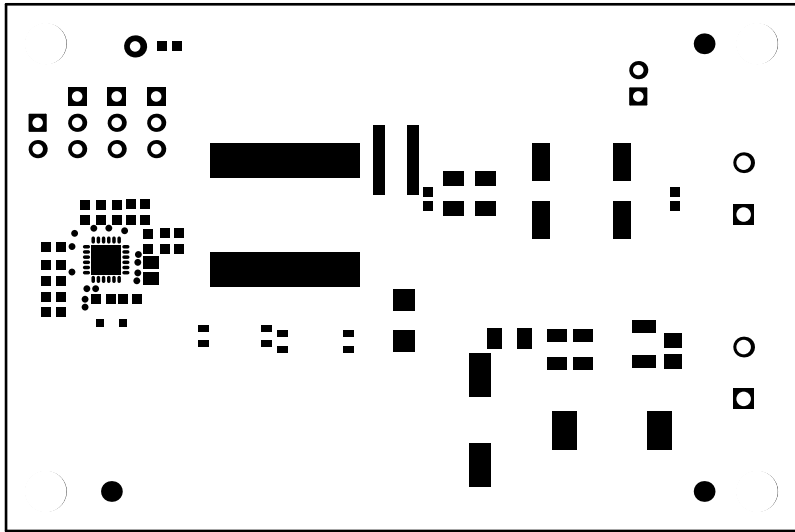
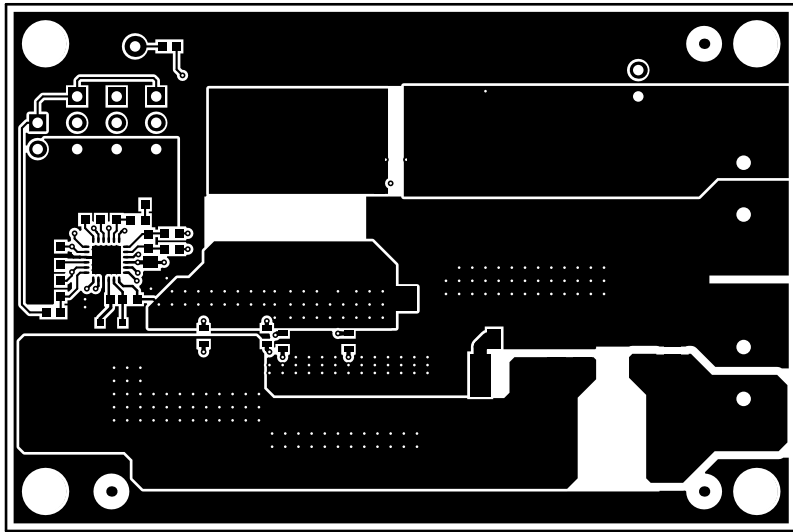


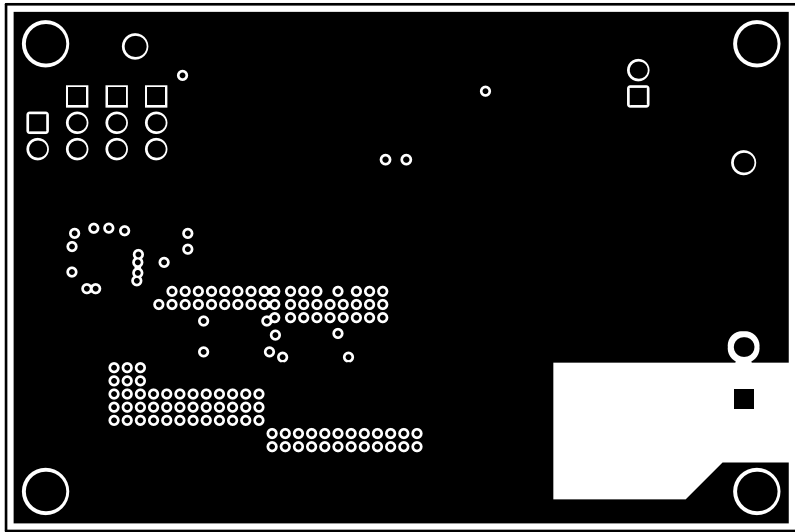
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 1/30/2017	9:35:18 AM	TEXAS INSTRUMENTS



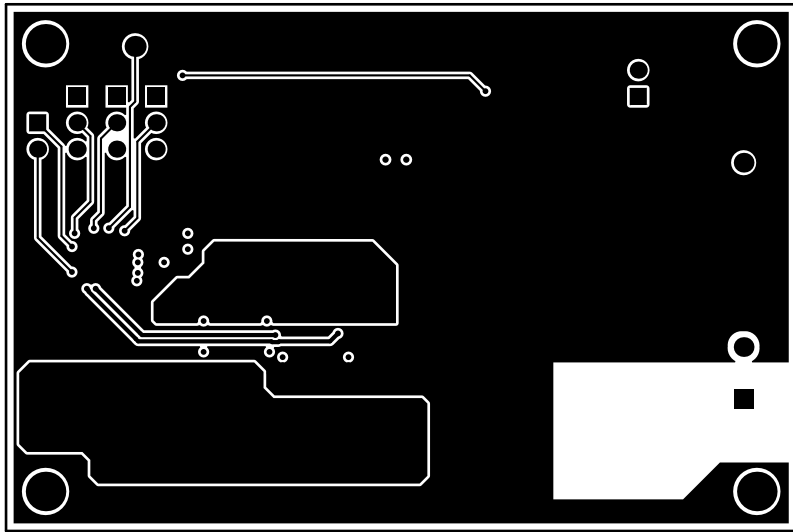
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 1/30/2017 9:35:19 AM	TEXAS INSTRUMENTS	



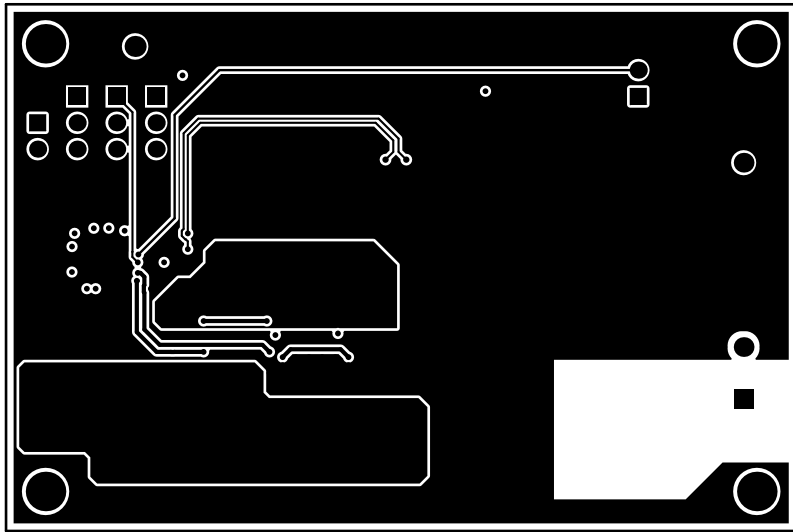
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 1/30/2017 9:35:19 AM	TEXAS INSTRUMENTS	



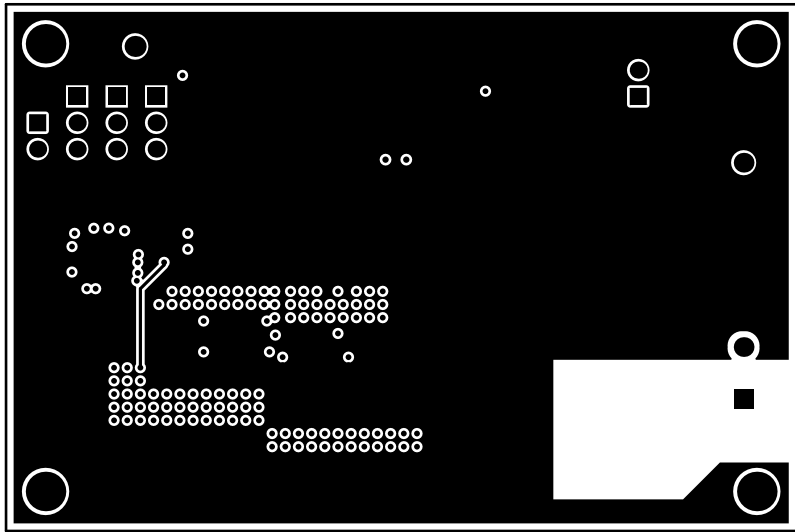
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: N/A		
PLOT NAME = Signal 1	GENERATED : 1/30/2017 9:35:20 AM	TEXAS INSTRUMENTS	



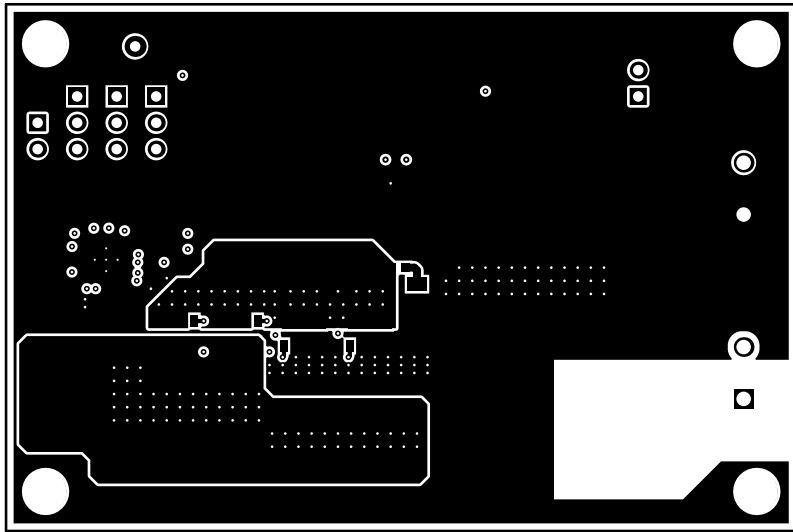
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: N/A		
PLOT NAME = Signal 2	GENERATED : 1/30/2017 9:35:21 AM	TEXAS INSTRUMENTS	



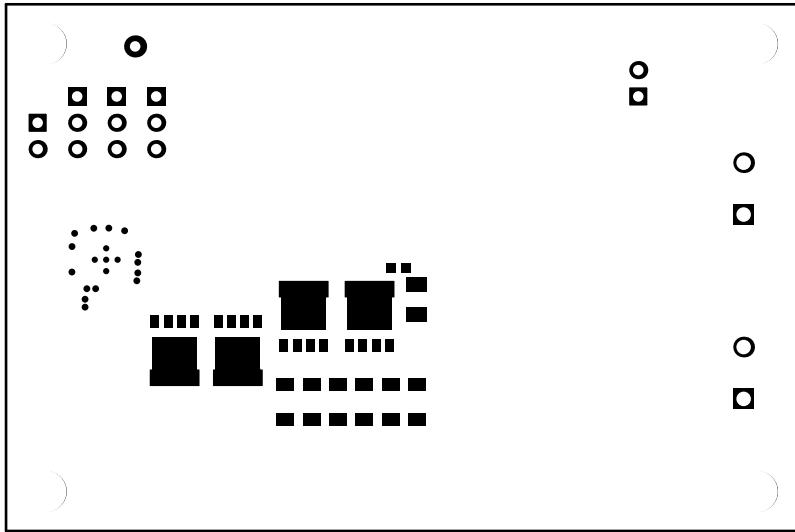
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 3	TID #: N/A		
PLOT NAME = Signal 3	GENERATED : 1/30/2017 9:35:21 AM	TEXAS INSTRUMENTS	



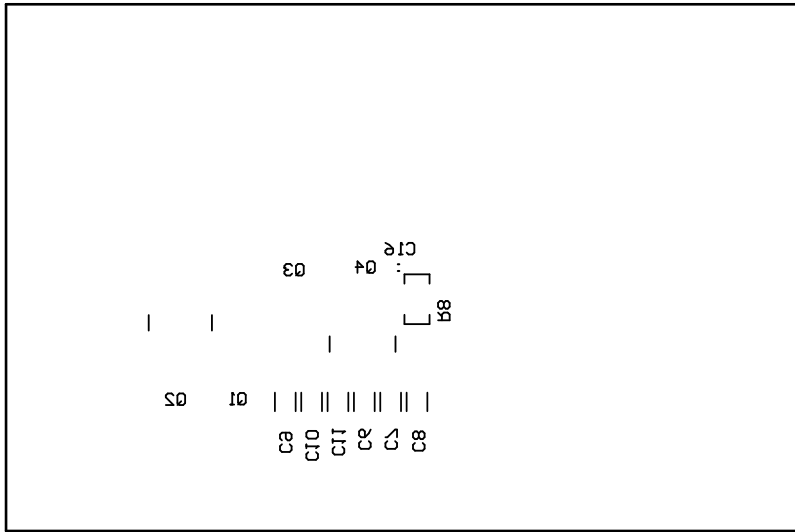
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 4	TID #: N/A		
PLOT NAME = Signal 4	GENERATED : 1/30/2017 9:35:22 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 1/30/2017 9:35:23 AM	TEXAS INSTRUMENTS	

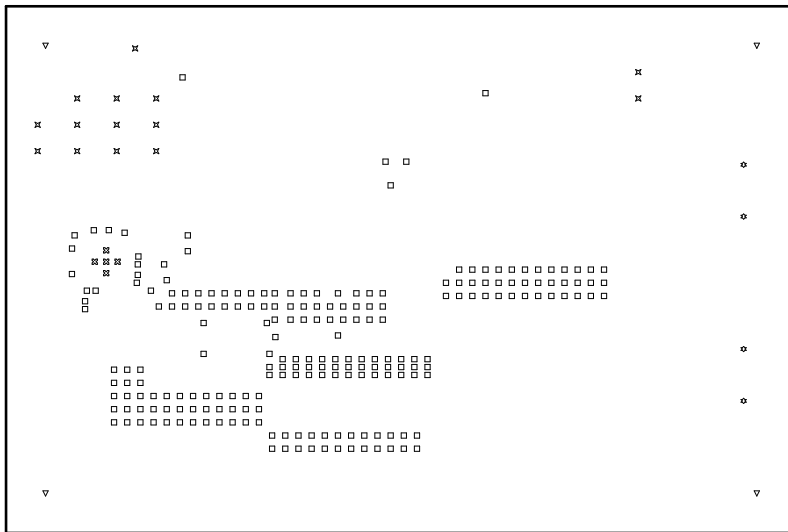


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 1/30/2017	9:35:23 AM	TEXAS INSTRUMENTS

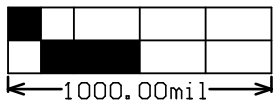


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 1/30/2017	9:35:24 AM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	4	159.00mil (4.039mm)	NPTH	Round
⊗	5	7.87mil (0.200mm)	PTH	Round
□	215	10.00mil (0.254mm)	PTH	Round
⊗	14	40.00mil (1.016mm)	PTH	Round
☆	4	55.12mil (1.400mm)	PTH	Round
	242 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 1/30/2017	9:35:25 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15019	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 1/30/2017	9:35:25 AM	TEXAS INSTRUMENTS

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